


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/22/13487	
<b>1.3 Title of PCN</b>	ST Ang Mo Kio (Singapore) additional wafer fab for industrial grade EEPROM products manufactured with CMOSF8H+ technology	
<b>1.4 Product Category</b>	Industrial grade EEPROM products manufactured with CMOSF8H+ - see Appendix B for product list	
<b>1.5 Issue date</b>	2022-06-08	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	KRAUSE INA
<b>2.1.2 Phone</b>	+49 89460062370
<b>2.1.3 Email</b>	ina.krause@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Benoit RODRIGUES
<b>2.1.2 Marketing Manager</b>	Philippe GANIVET
<b>2.1.3 Quality Manager</b>	Rita PAVANO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ST Singapore 8inch fab (SG8E)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	The M24128, M24C16, M24C04, M24C02 industrial grade EEPROM currently produced with CMOSF8H+ process technology in ST Rousset 8 inch Fab (R8)...	...will be also produced with same process technology in ST Singapore 8inch fab (SG8E).  Die design remains unchanged. Electrical Wafer Sort, Assembly and Final test remain unchanged.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	- Form: Marking change for SO8N, no change for TSSOP8 and DFN8 - Fit: No change - Function: No change	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	The strategy of the STMicroelectronics Memory division is to support our customers on product and service quality on a long-term basis. In line with this commitment, this Front-end manufacturing double source introduction will increase wafer manufacturing capacity and contribute to EEPROM business continuity security (BCP).
<b>5.2 Customer Benefit</b>	DOUBLE SOURCING

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	new FG on box label
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-06-06
<b>7.2 Intended start of delivery</b>	2022-09-05
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	
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8.2 Qualification report and qualification results	In progress	Issue Date	
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<b>9. Attachments (additional documentations)</b>
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13487 Public product.pdf 13487 PCN SGE8 with Qual Report.pdf
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<b>10. Affected parts</b>
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10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-BFMC6TG	
	M24128-BRDW6TP	
	M24128-BWDW6TP	
3335794	M24C02-WMN6TP	

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